

RADIAL CONTACT PAD FOOTPRINT AND WIRING FOR ELECTRICAL COMPONENTS

Abstract of the Disclosure

5 A structure and associated method comprising contact pads on a surface of a substrate for
coupling signal, power, and ground connections for an electrical device to a plurality of
conductive wires on the substrate. The contact pads are formed in single lines along radial edges
of sectors on the substrate. Each of the sectors comprise a predetermined angle between the
radial edges of each of the sectors. The plurality of sectors collectively form a circular area. The
contact pads comprise signal, power, and ground connections located at predetermined positions
10 on the single lines along the radial edges of each of the sectors on the substrate.